

NCA9555-Q100

Low-voltage 16-bit I²C and SMBus I/O expander with interrupt output and configuration registers

Rev. 3.1 — 5 August 2024

Product data sheet

1. General description

The NCA9555-Q100 provides 16 bits of General Purpose Input/Output (GPIO) expansion for I²C-bus/SMBus applications. It is designed for a wide voltage range of 1.65 V to 5.5 V with interrupt and default pull-up resistors on GPIOs. Nexperia GPIO expanders provide an elegant solution when additional IOs are needed while keeping the interconnections to a minimum, for example, in ACPI power switches, sensors, push buttons, LEDs and fan control. The NCA9555-Q100 contains a set of 8 bit input, output, configuration and polarity inversion registers. At power up all IOs default to inputs. Each IO can be configured as either input or output by changing the corresponding bit in the configuration register. The data for each input or output is stored in the corresponding input or output register. The polarity inversion register can be programmed to invert the polarity of the input register. The NCA9555-Q100 has an open-drain interrupt output which is activated when any one of the GPIO changes from its corresponding input port register state. The power on reset sets the registers to default values and initializes the device state machine. The NCA9555-Q100 has three address pins A0, A1 and A2 which can be used to configure the I²C bus slave address of the device. It allows up-to eight devices to share the same I²C-bus/SMBus.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

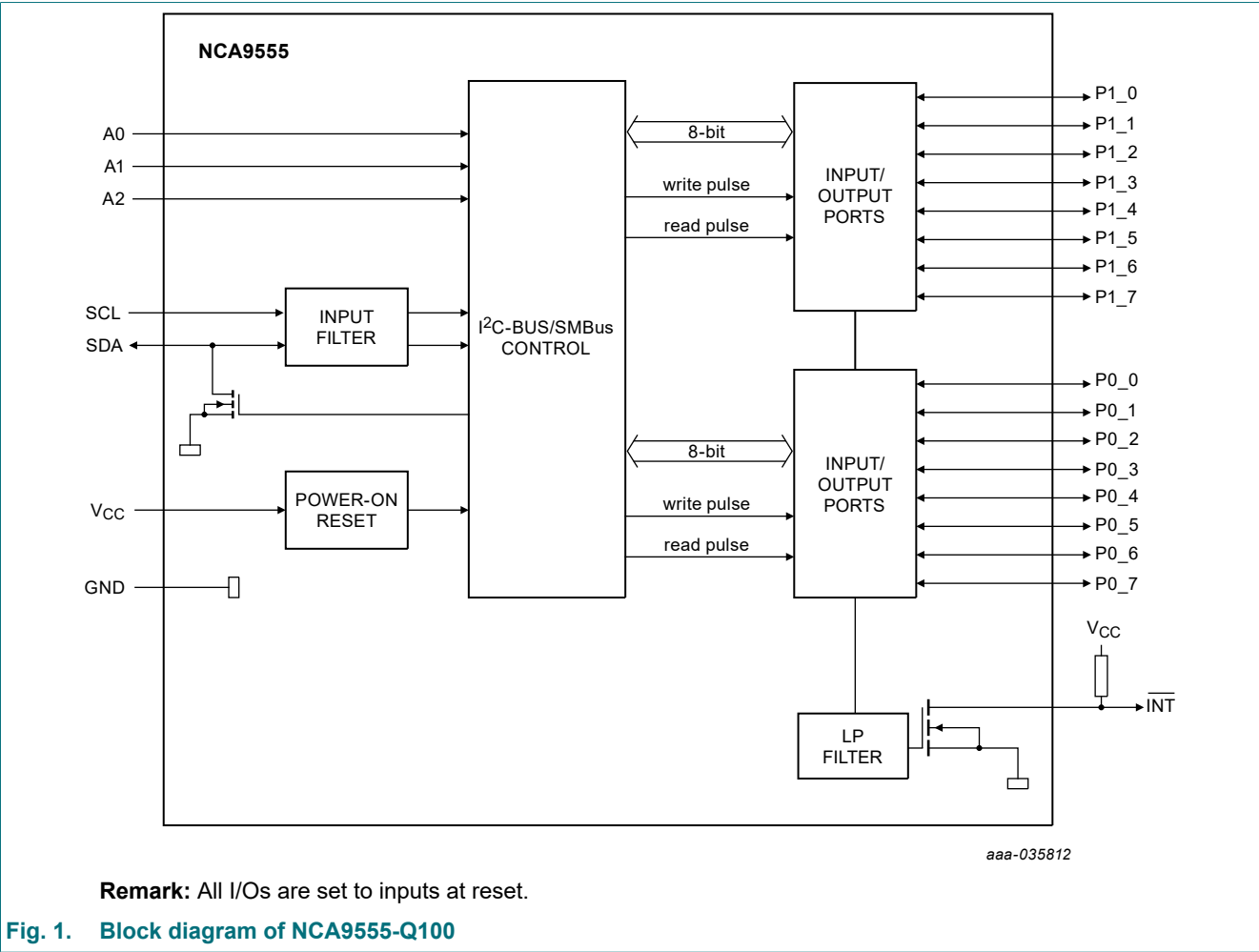
- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Specified from -40 °C to +125 °C
- I²C-bus to parallel port expander
- Operating power supply voltage range of 1.65 V to 5.5 V
- Low standby current consumption:
 - 4.0 µA (maximum)
- Schmitt-trigger action allows slow input transition and better switching noise immunity at the SCL and SDA inputs
 - $V_{hys} = 0.10 \times V_{CC}$ (typical)
 - Noise filter on SCL and SDA inputs
- 5 V tolerant I/Os
- 16 I/O pins which power up configured in input state with weak pull-up resistor
- Open-drain active LOW interrupt output ($\overline{INT}$)
- 400 kHz Fast-mode I²C-bus
- Internal power-on reset
- No glitch on power-up
- Latched outputs with 25 mA drive maximum capability for directly driving LEDs
- Latch-up performance exceeds 100 mA per JESD78, Class II
- ESD protection:
 - HBM ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
 - CDM ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V

3. Ordering information

Table 1. Ordering information

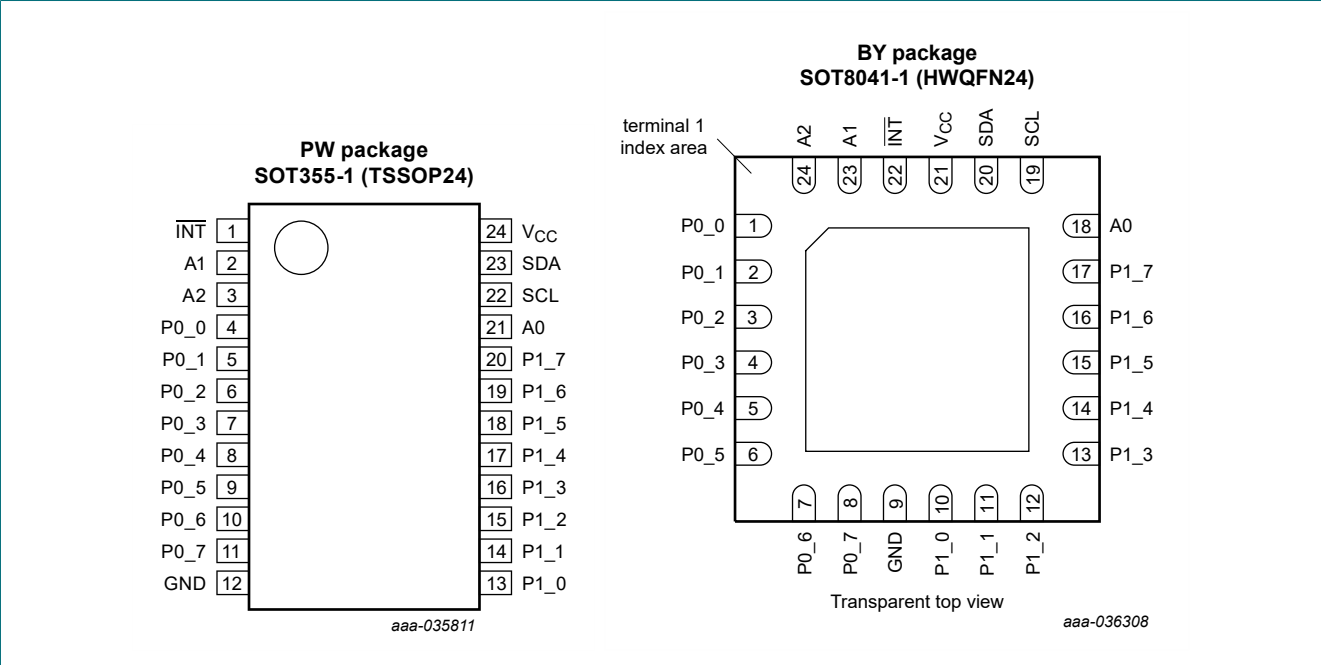
Type number	Package			
	Temperature range	Name	Description	Version
NCA9555PW-Q100	-40 °C to +125 °C	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1
NCA9555BY-Q100	-40 °C to +125 °C	HWQFN24	plastic thermal enhanced very very thin Quad Flat packages; no leads; 24 terminals; 0.5 mm pitch; 4 × 4 × 0.75 mm body	SOT8041-1

4. Block diagram



5. Pinning information

5.1. Pinning



5.2. Pin description

Table 2. Pin description

Symbol	Pin		Type	Description
	TSSOP24	HWQFN24		
INT	1	22	O	Interrupt output. Connect to V _{CC} through a pull-up resistor
A1	2	23	I	Address input 1. Connect directly to V _{CC} or GND
A2	3	24	I	Address input 2. Connect directly to V _{CC} or GND
P0_0 [1]	4	1	I/O	Parallel port I/O. Push-pull driver. At power on, P0_0 is configured as input
P0_1 [1]	5	2	I/O	Parallel port I/O. Push-pull driver. At power on, P0_1 is configured as input
P0_2 [1]	6	3	I/O	Parallel port I/O. Push-pull driver. At power on, P0_2 is configured as input
P0_3 [1]	7	4	I/O	Parallel port I/O. Push-pull driver. At power on, P0_3 is configured as input
P0_4 [1]	8	5	I/O	Parallel port I/O. Push-pull driver. At power on, P0_4 is configured as input
P0_5 [1]	9	6	I/O	Parallel port I/O. Push-pull driver. At power on, P0_5 is configured as input
P0_6 [1]	10	7	I/O	Parallel port I/O. Push-pull driver. At power on, P0_6 is configured as input
P0_7 [1]	11	8	I/O	Parallel port I/O. Push-pull driver. At power on, P0_7 is configured as input
GND	12	9 [2]	power	Ground
P1_0 [3]	13	10	I/O	Parallel port I/O. Push-pull driver. At power on, P1_0 is configured as input
P1_1 [3]	14	11	I/O	Parallel port I/O. Push-pull driver. At power on, P1_1 is configured as input
P1_2 [3]	15	12	I/O	Parallel port I/O. Push-pull driver. At power on, P1_2 is configured as input
P1_3 [3]	16	13	I/O	Parallel port I/O. Push-pull driver. At power on, P1_3 is configured as input
P1_4 [3]	17	14	I/O	Parallel port I/O. Push-pull driver. At power on, P1_4 is configured as input
P1_5 [3]	18	15	I/O	Parallel port I/O. Push-pull driver. At power on, P1_5 is configured as input

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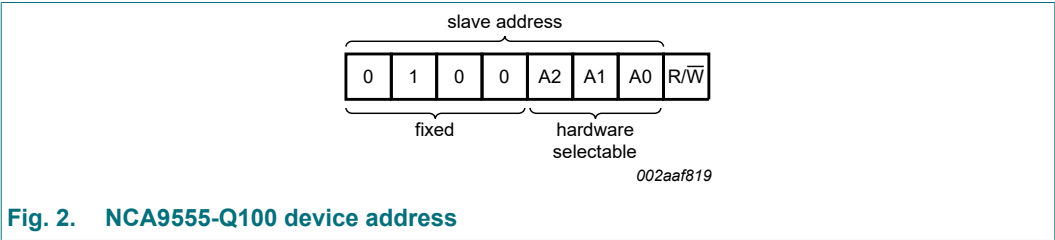
Symbol	Pin		Type	Description
	TSSOP24	HWQFN24		
P1_6 [3]	19	16	I/O	Parallel port I/O. Push-pull driver. At power on, P1_6 is configured as input
P1_7 [3]	20	17	I/O	Parallel port I/O. Push-pull driver. At power on, P1_7 is configured as input
A0	21	18	I	Address input 0. Connect directly to V _{CC} or GND
SCL	22	19	I	Serial clock bus. Connect to V _{CC} through a pull-up resistor
SDA	23	20	I/O	Serial data bus. Connect to V _{CC} through a pull-up resistor.
V _{CC}	24	21	power	Supply voltage.

- [1] Pins P0_0 to P0_7 correspond to bits P0.0 to P0.7. At power-up, all I/O are configured as high-impedance inputs.
- [2] HWQFN24 package die supply ground is connected to both GND pin and exposed center pad. GND pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board and for proper heat conduction through the board, thermal vias need to be incorporated in the PCB in the thermal pad region.
- [3] Pins P1_0 to P1_7 correspond to bits P1.0 to P1.7. At power-up, all I/O are configured as high-impedance inputs.

6. Functional description

For the block diagram of the NCA9555-Q100 see [Fig. 1](#).

6.1. Device address



A2, A1 and A0 are the hardware address package pins and are held to either HIGH (logic 1) or LOW (logic 0) to assign one of the eight possible slave addresses. The last bit of the slave address (R/W) defines the operation (read or write) to be performed. A HIGH (logic 1) selects a read operation, while a LOW (logic 0) selects a write operation.

6.2. Registers

6.2.1. Pointer register and command byte

Following the successful acknowledgement of the address byte, the bus master sends a command byte, which is stored in the address pointer register of the NCA9555-Q100. The lower three bits of this data byte state the operation (read or write) and the internal registers (Input, Output, Polarity Inversion, or Configuration) that will be affected. This register is write only.

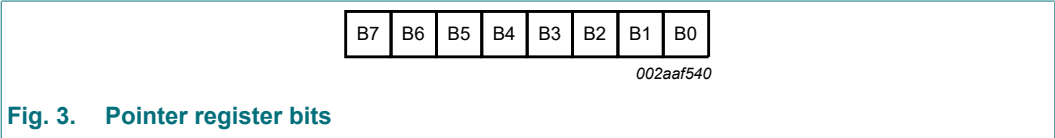


Table 3. Command byte

Pointer register bits								Command byte (hexadecimal)	Register	Protocol	Power-up default
B7	B6	B5	B4	B3	B2	B1	B0				
0	0	0	0	0	0	0	0	00h	Input port 0	read byte	xxxx xxxx [1]
0	0	0	0	0	0	0	1	01h	Input port 1	read byte	xxxx xxxx
0	0	0	0	0	0	1	0	02h	Output port 0	read/write byte	1111 1111
0	0	0	0	0	0	1	1	03h	Output port 1	read/write byte	1111 1111
0	0	0	0	0	1	0	0	04h	Polarity Inversion port 0	read/write byte	0000 0000
0	0	0	0	0	1	0	1	05h	Polarity Inversion port 1	read/write byte	0000 0000
0	0	0	0	0	1	1	0	06h	Configuration port 0	read/write byte	1111 1111
0	0	0	0	0	1	1	1	07h	Configuration port 1	read/write byte	1111 1111

[1] The default value 'X' is determined by the externally applied logic level.

6.2.2. Input port register pair (00h, 01h)

The Input port registers (registers 0 and 1) reflect the logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration register. The Input port registers are read only; writes to these registers have no effect. The default value 'X' is determined by the externally applied logic level. An Input port register read operation is performed as described in [Section 7.2](#).

Table 4. Input port 0 register (address 00h)

Bit	7	6	5	4	3	2	1	0
Symbol	I0.7	I0.6	I0.5	I0.4	I0.3	I0.2	I0.1	I0.0
Default	X	X	X	X	X	X	X	X

Table 5. Input port 1 register (address 01h)

Bit	7	6	5	4	3	2	1	0
Symbol	I1.7	I1.6	I1.5	I1.4	I1.3	I1.2	I1.1	I1.0
Default	X	X	X	X	X	X	X	X

6.2.3. Output port register pair (02h, 03h)

The Output port registers (registers 2 and 3) define the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in these registers have no effect on pins defined as inputs. In turn, reads from these registers reflect the value that was written to these registers, **not** the actual pin value. A register pair write is described in [Section 7.1](#) and a register pair read is described in [Section 7.2](#).

Table 6. Output port 0 register (address 02h)

Bit	7	6	5	4	3	2	1	0
Symbol	O0.7	O0.6	O0.5	O0.4	O0.3	O0.2	O0.1	O0.0
Default	1	1	1	1	1	1	1	1

Table 7. Output port 1 register (address 03h)

Bit	7	6	5	4	3	2	1	0
Symbol	O1.7	O1.6	O1.5	O1.4	O1.3	O1.2	O1.1	O1.0
Default	1	1	1	1	1	1	1	1

6.2.4. Polarity inversion register pair (04h, 05h)

The Polarity inversion registers (registers 4 and 5) allow polarity inversion of pins defined as inputs by the Configuration register. If a bit in these registers is set (written with '1'), the corresponding port pin's polarity is inverted in the Input register. If a bit in this register is cleared (written with a '0'), the corresponding port pin's polarity is retained. A register pair write is described in [Section 7.1](#) and a register pair read is described in [Section 7.2](#).

Table 8. Polarity inversion port 0 register (address 04h)

Bit	7	6	5	4	3	2	1	0
Symbol	N0.7	N0.6	N0.5	N0.4	N0.3	N0.2	N0.1	N0.0
Default	0	0	0	0	0	0	0	0

Table 9. Polarity inversion port 1 register (address 05h)

Bit	7	6	5	4	3	2	1	0
Symbol	N1.7	N1.6	N1.5	N1.4	N1.3	N1.2	N1.1	N1.0
Default	0	0	0	0	0	0	0	0

6.2.5. Configuration register pair (06h, 07h)

The Configuration registers (registers 6 and 7) configure the direction of the I/O pins. If a bit in these registers is set to 1, the corresponding port pin is enabled as a high-impedance input. If a bit in these registers is cleared to 0, the corresponding port pin is enabled as an output. A register pair write is described in [Section 7.1](#) and a register pair read is described in [Section 7.2](#).

Table 10. Configuration port 0 register (address 06h)

Bit	7	6	5	4	3	2	1	0
Symbol	C0.7	C0.6	C0.5	C0.4	C0.3	C0.2	C0.1	C0.0
Default	1	1	1	1	1	1	1	1

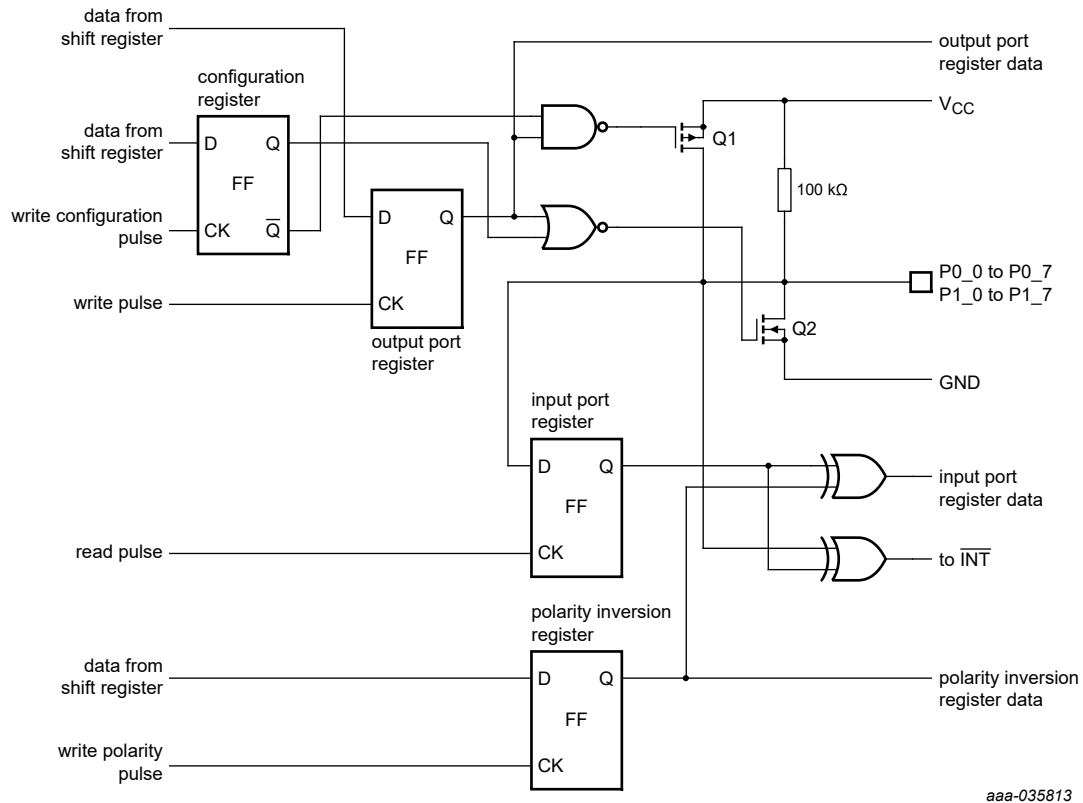
Table 11. Configuration port 1 register (address 07h)

Bit	7	6	5	4	3	2	1	0
Symbol	C1.7	C1.6	C1.5	C1.4	C1.3	C1.2	C1.1	C1.0
Default	1	1	1	1	1	1	1	1

6.3. I/O port

When an I/O is configured as an input, FETs Q1 and Q2 are off, which creates a high-impedance input. The input voltage may be raised above V_{CC} to a maximum of 5.5 V.

If the I/O is configured as an output, Q1 or Q2 is enabled, depending on the state of the Output port register. In this case, there are low-impedance paths between the I/O pin and either V_{CC} or GND. The external voltage applied to this I/O pin should not exceed the recommended levels for proper operation.



At power-on reset, all registers return to default values.

Fig. 4. Simplified schematic of the I/Os (P0_0 to P0_7, P1_0 to P1_7)

6.4. Power-on reset

When power (from 0 V) is applied to V_{CC} and starts rising, an internal power-on reset holds the NCA9555-Q100 in a reset condition until V_{CC} has reached V_{PORR} . At that time, the reset condition is released and the NCA9555-Q100 registers and I²C-bus/SMBus state machine initializes to their default states. After that, V_{CC} must be lowered to below V_{PORF} and back up to the operating voltage for a power-reset cycle. See [Section 8.2](#).

6.5. Interrupt output

An interrupt is generated by any rising or falling edge of the port inputs in the Input mode. After time $t_{V(INT)}$, the signal $\overline{INT}$ is valid. The interrupt is reset when data on the port changes back to the original value or when data is read from the port that generated the interrupt (see [Fig. 8](#) and [Fig. 9](#)). Resetting occurs in the Read mode at the acknowledge (ACK) or not acknowledge (NACK) bit after the rising edge of the SCL signal. Interrupts that occur during the ACK or NACK clock pulse can be lost (or be very short) due to the resetting of the interrupt during this pulse. Any change of the I/Os after resetting is detected and is transmitted as $\overline{INT}$.

A pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur, if the state of the pin does not match the contents of the Input Port register.

7. Bus transactions

The NCA9555-Q100 is an I²C-bus slave device. Data is exchanged between the master and NCA9555-Q100 through write and read commands using I²C-bus. The two communication lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

7.1. Writing to the port registers

Data is transmitted to the NCA9555-Q100 by sending the start condition, device address and setting the read-write bit to a logic 0 (see [Fig. 2](#)). The command byte is sent after the address and determines which register will receive the data following the command byte.

Eight registers within the NCA9555-Q100 are configured to operate as four register pairs. The four pairs are input port, output port, polarity inversion, configuration registers. After sending data to one register, the next data byte is sent to the other register in the pair (see [Fig. 5](#) and [Fig. 6](#)). For example, if the first byte is sent to Output Port 1 (register 3), the next byte is stored in Output Port 0 (register 2).

There is no limitation on the number of data bytes sent in one write transmission. In this way, the host can continuously update a register pair independently of the other registers, or the host can simply update a single register.

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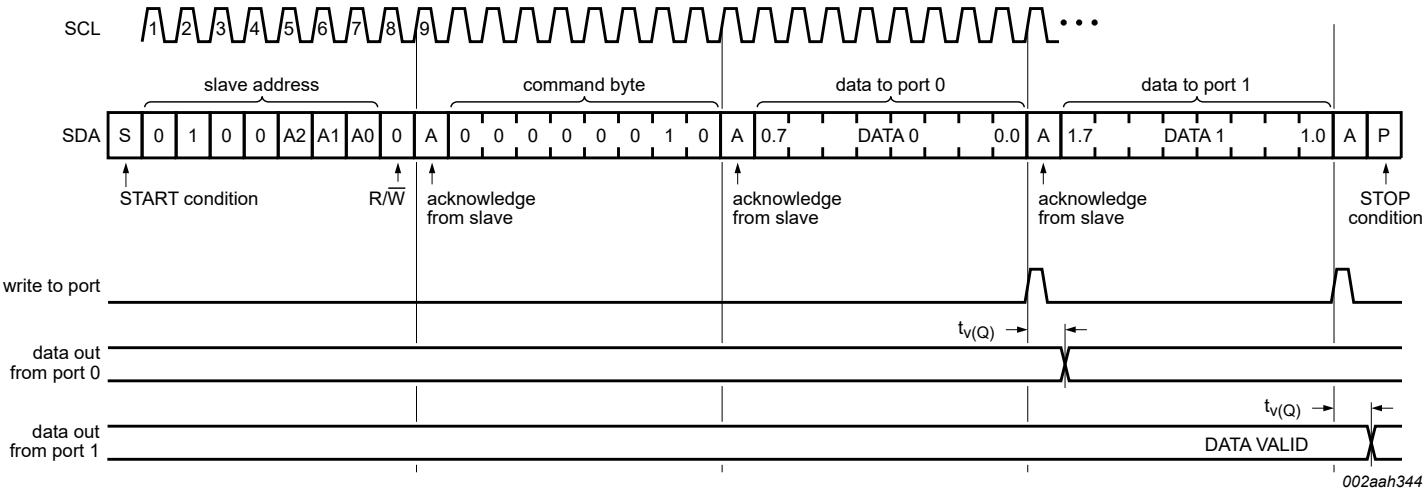


Fig. 5. Write to output port registers

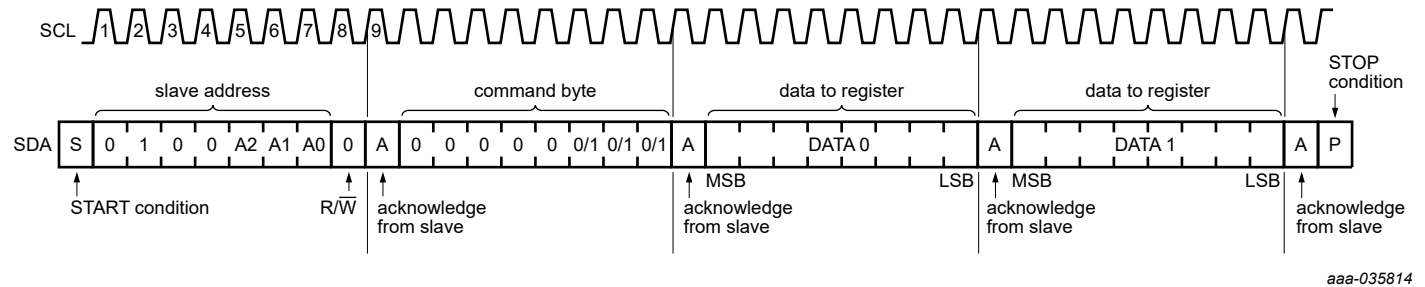
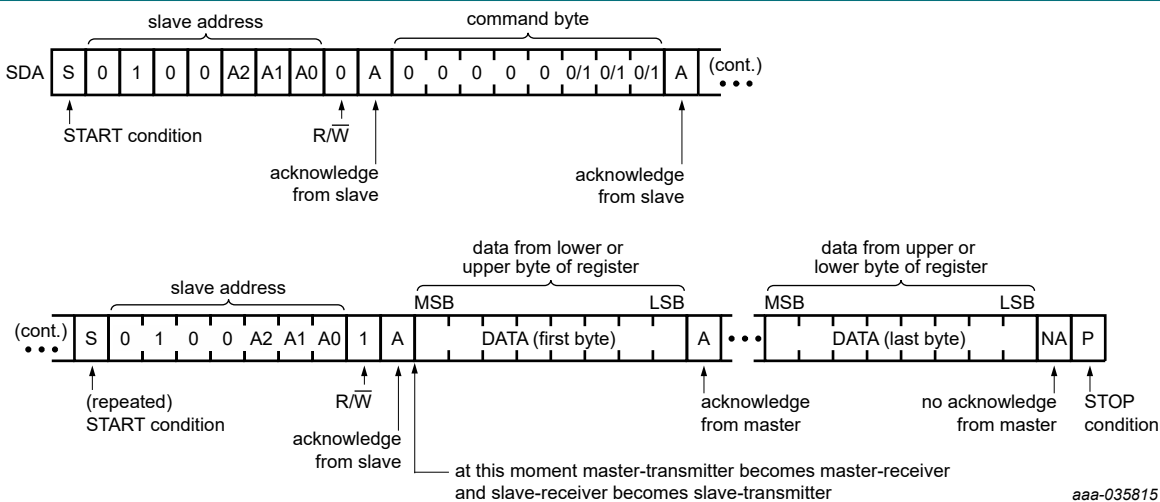


Fig. 6. Write to Control registers

7.2. Reading the port registers

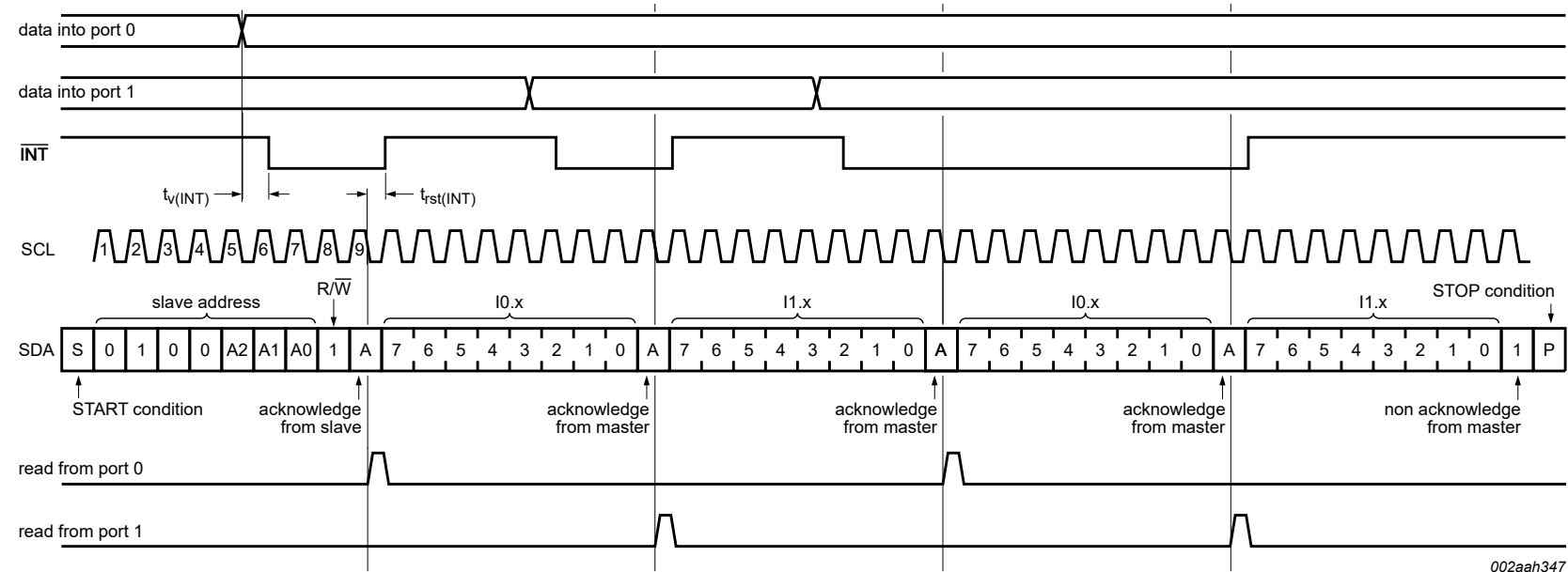
In order to read data from the NCA9555-Q100, the bus master must first send the start condition, NCA9555-Q100 address with the read-write bit set to a logic 0 (see Fig. 2). The command byte is sent after the address and determines which register will be accessed. After a start or restart, the device address is sent again, but this time the least significant bit is set to a logic 1. Data from the register defined by the command byte is sent by the NCA9555-Q100 (see Fig. 7, Fig. 8 and Fig. 9). Data is clocked into the register on the rising edge of the acknowledge clock pulse. After the first byte is read, additional bytes may be read but the data now reflects the information in the other register in the pair. For example, if Input Port 1 is read, the next byte read is Input Port 0. There is no limit on the number of data bytes received in one read transmission, but on the final byte received the bus master must not acknowledge the data.

After a subsequent start or restart, the command byte contains the value of the next register to be read in the pair. For example, if Input Port 1 was read last before the restart, the register that is read after the restart is the Input Port 0.



Remark: Transfer can be stopped at any time by a STOP condition.

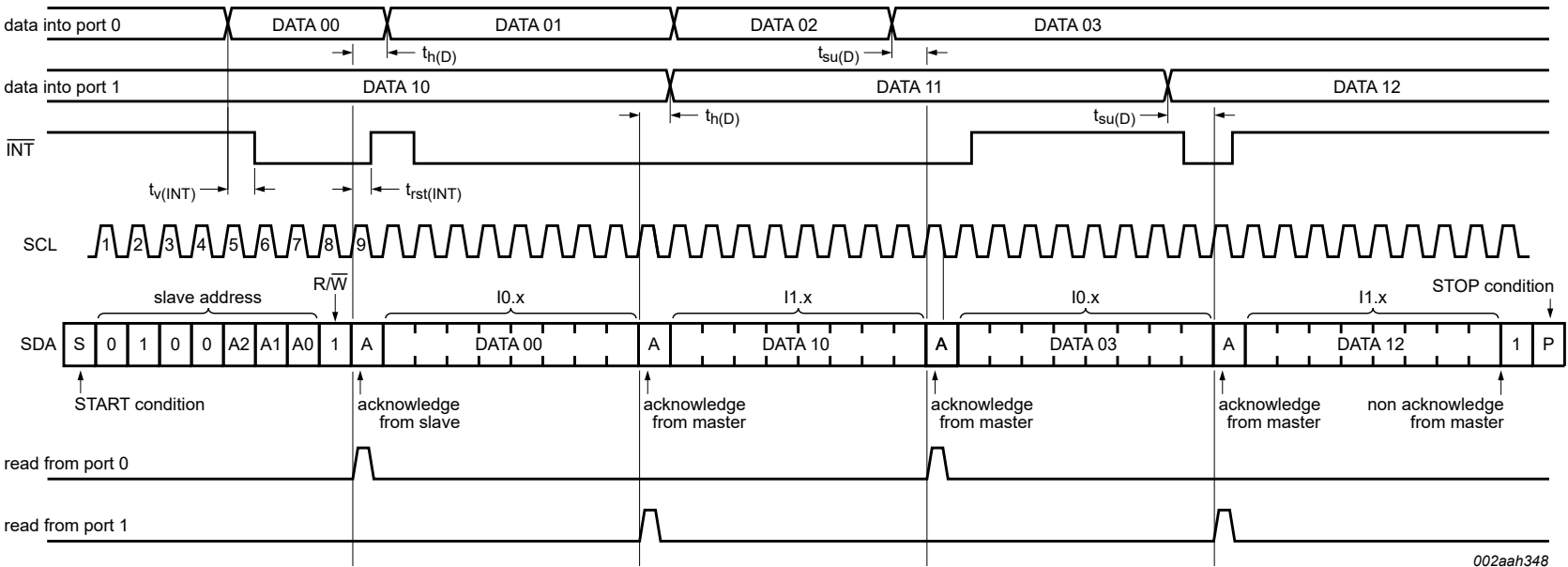
Fig. 7. Read from register



Remark: Transfer of data can be stopped at any moment by a STOP condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte has previously been set to '00h' (read input port register). This figure eliminates the command byte transfer and a restart between the initial slave address call and the actual data transfer from P port (see Fig. 7).

Fig. 8. Read input port register, scenario 1

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Remark: Transfer of data can be stopped at any moment by a STOP condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte has previously been set to '00h' (read input port register). This figure eliminates the command byte transfer and a restart between the initial slave address call and the actual data transfer from P port (see Fig. 7).

Fig. 9. Read input port register, scenario 2

8. Application design-in information

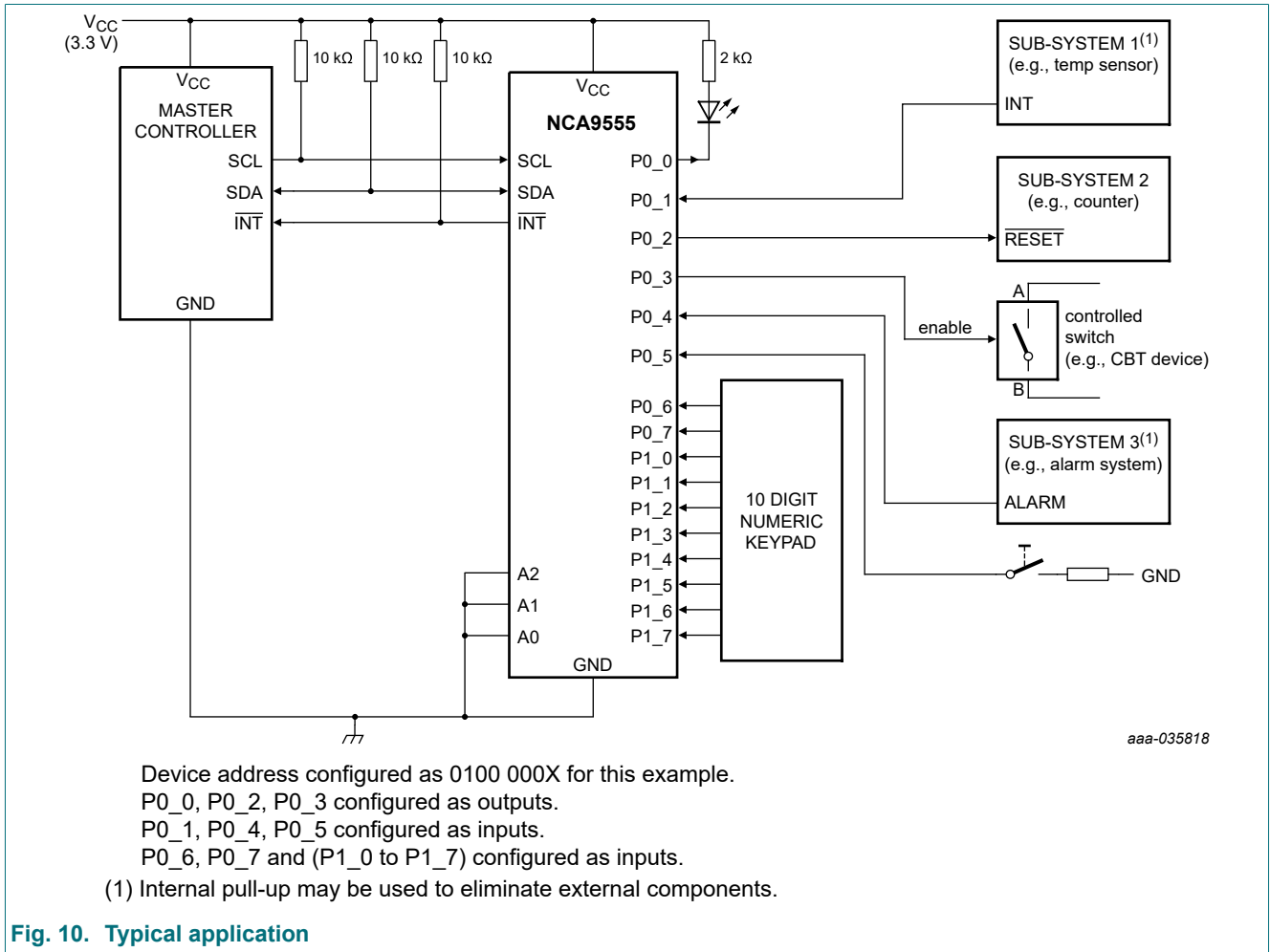
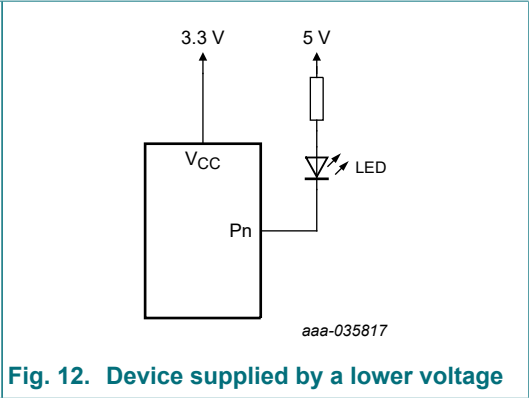
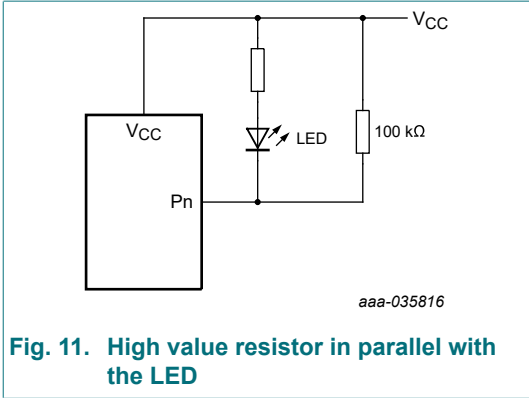


Fig. 10. Typical application

8.1. Minimizing I_{CC} when the I/Os are used to control LEDs

When the I/Os are used to control LEDs, they are normally connected to V_{CC} through a resistor as shown in Fig. 10. Since the LED acts as a diode, when the LED is off the I/O V_I is about 1.2 V less than V_{CC} . The supply current, I_{CC} , increases as V_I becomes lower than V_{CC} .

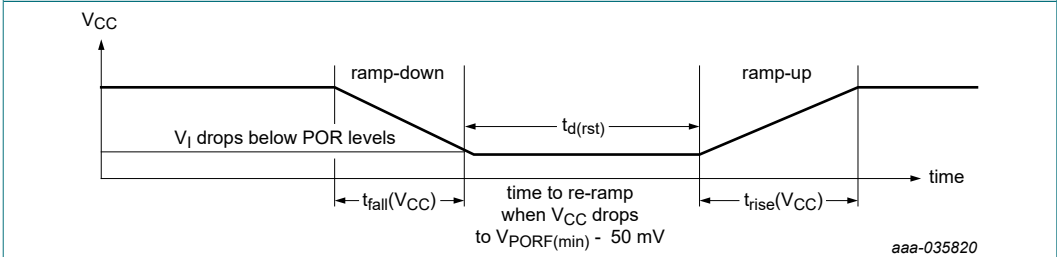
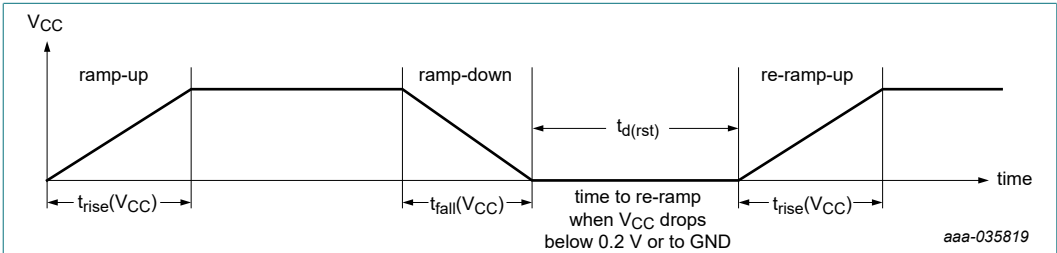
Designs needing to minimize current consumption, such as battery power applications, should consider maintaining the I/O pins greater than or equal to V_{CC} when the LED is off. Fig. 11 shows a high value resistor in parallel with the LED. Fig. 12 shows V_{CC} less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O V_I at or above V_{CC} and prevents additional supply current consumption when the LED is off.



8.2. Power-on reset requirements

In the event of a glitch or data corruption, NCA9555-Q100 can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

The two types of power-on reset are shown in [Fig. 13](#) and [Fig. 14](#).



[Table 12](#) specifies the performance of the power-on reset feature for NCA9555-Q100 for both types of power-on reset.

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Table 12. Recommended supply sequencing and ramp rates

$T_{amb} = 25\text{ °C}$ (unless otherwise noted). Not tested; specified by design.

Symbol	Parameter	Condition	$T_{amb} = 25\text{ °C}$			Unit
			Min	Typ	Max	
$t_{rise}(V_{CC})$	supply ramp up time	Fig. 13	0.1	-	2000	ms
$t_{fall}(V_{CC})$	supply ramp down time	Fig. 13	0.1	-	2000	ms
$t_{d(rst)}$	reset delay time	Fig. 13 ; re-ramp time when V_{CC} drops below 0.2 V or to GND	1	-	-	μs
		Fig. 14 ; re-ramp time when V_{CC} drops to $V_{POR(min)} - 50\text{ mV}$	1	-	-	μs
$\Delta V_{CC(gl)}$	glitch supply voltage difference	Fig. 15	-	-	1	V
$V_{CC_MIN(gl)}$	minimum glitch supply voltage	minimum voltage that V_{CC} can glitch down to, but not cause functional disruption when $t_{w(gl)}V_{CC}$ Fig. 15	1.5	-	-	V
$t_{w(gl)}V_{CC}$	supply voltage glitch pulse width	Fig. 15	-	-	10	μs

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width ($t_{w(gl)}V_{CC}$) and glitch height ($\Delta V_{CC(gl)}$) are dependent on each other. The glitch on power supply should never go below $V_{CC_MIN(gl)}$ in order to properly guarantee functionality. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. [Fig. 15](#) and [Table 12](#) provide more information on how to measure these specifications.

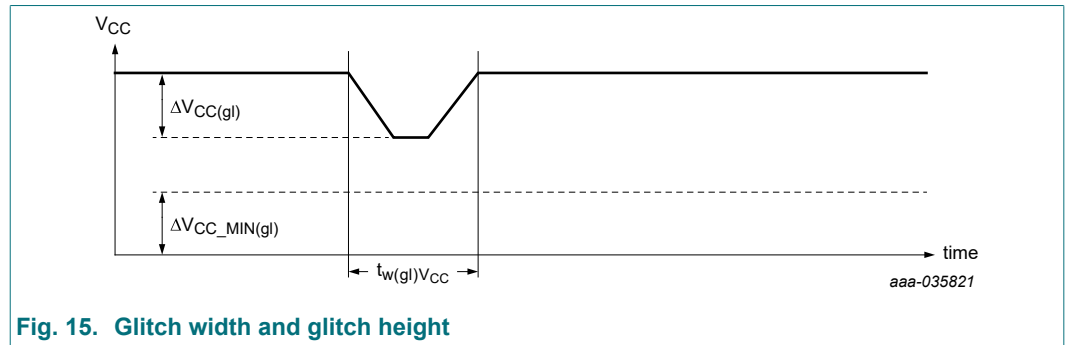


Fig. 15. Glitch width and glitch height

V_{PORR} and V_{PORF} are critical to the power-on reset. V_{PORR} is the voltage level of V_{CC} at which the reset condition is released and all the registers and the I²C-bus/SMBus state machine are initialized to their default states. V_{PORF} is the voltage level of V_{CC} below which NCA9555-Q100 enters reset state. [Fig. 16](#) and [Section 12](#) provide more details on this specification.

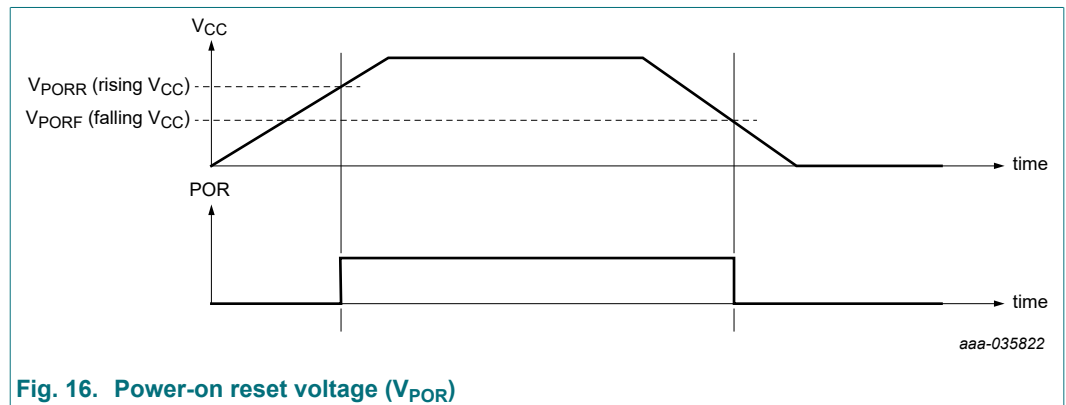


Fig. 16. Power-on reset voltage (V_{POR})

8.3. Device current consumption with internal pull-up and pull-down resistors

The NCA9555-Q100 integrates pull-up resistors to eliminate external components when pins are configured as inputs and pull-up resistors are required (for example, nothing is driving the inputs to the power supply rails. Since these pull-up resistors are internal to the device itself, they contribute to the current consumption of the device and must be considered in the overall system design.

If the resistor is configured as a pull-up, that is, connected to V_{CC} , a current will flow from the V_{CC} pin through the resistor to ground when the pin is held LOW. This current will appear as additional I_{CC} upsetting any current consumption measurements.

The pull-up resistors are simple resistors and the current is linear with voltage. The resistance specification for these devices spans from 50 k Ω with a nominal 100 k Ω value. Any current flow through these resistors is additive by the number of pins held LOW and the current can be calculated by Ohm's law. See [Fig. 20](#) for a graph of supply current versus the number of pull-up resistors.

9. Limiting values

Table 13. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	6	V
V_I	input voltage	[1]	-0.5	6	V
V_O	output voltage	[1]	-0.5	6	V
I_{IK}	input clamping current	A0, A1, A2, SCL; $V_I < 0$ V	-	-20	mA
I_{OK}	output clamping current	INT; $V_O < 0$ V	-	-20	mA
I_{IOK}	input/output clamping current	P port; $V_O < 0$ V or $V_O > V_{CC}$	-	± 20	mA
		SDA; $V_O < 0$ V	-	-20	mA
I_{OL}	LOW-level output current	continuous; I/O port	-	50	mA
		continuous; SDA, INT	-	25	mA
I_{OH}	HIGH-level output current	continuous; P port	-	25	mA
I_{CC}	supply current		-	160	mA
I_{SS}	ground supply current		-	250	mA
P_{tot}	total power dissipation		-	200	mW
T_{stg}	storage temperature		-65	+150	°C
$T_{j(max)}$	maximum junction temperature		-	135	°C
T_{amb}	ambient temperature	operating in free air	-40	+125	°C

[1] The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

10. Recommended operating conditions

Table 14. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		1.65	5.5	V
V _{IH}	HIGH-level input voltage	SCL, SDA	0.7 × V _{CC}	5.5	V
		P1_7 to P0_0	0.7 × V _{CC}	5.5	V
		A0, A1, A2,	0.7 × V _{CC}	V _{CC}	V
V _{IL}	LOW-level input voltage	SCL, SDA	-0.5	0.3 × V _{CC}	V
		A0, A1, A2, P1_7 to P0_0	-0.5	0.3 × V _{CC}	V
I _{OH}	HIGH-level output current	P1_7 to P0_0	-	10	mA
I _{OL}	LOW-level output current	P1_7 to P0_0	-	25	mA

11. Thermal characteristics

Table 15. Thermal characteristics

Symbol	Parameter	Conditions	Max	Unit
Z _{th(j-a)}	transient thermal impedance from junction to ambient	TSSOP24 package [1]	100	K/W
		HWQFN24 package [1]	32.6	K/W

[1] The package thermal impedance is calculated in accordance with JESD 51-7.

12. Static characteristics

Table 16. Static characteristics
 $V_{CC} = 1.65\text{ V to }5.5\text{ V}$; unless otherwise specified.

Symbol	Parameter	Conditions	$T_{amb} = -40\text{ °C to }+125\text{ °C}$			Unit
			Min	Typ [1]	Max	
V_{IK}	input clamping voltage	$I_I = -18\text{ mA}$	-1.2	-	-	V
V_{PORF}	power-on reset trip voltage; V_{CC} falling	$V_I = V_{CC}$ or GND; $I_O = 0\text{ mA}$	0.8	1.1	-	V
V_{PORR}	power-on reset trip voltage; V_{CC} rising	$V_I = V_{CC}$ or GND; $I_O = 0\text{ mA}$	-	1.25	1.6	V
I_{OL}	LOW-level output current	$V_{OL} = 0.4\text{ V}$; $V_{CC} = 1.65\text{ V to }5.5\text{ V}$				
		SDA	3	-	-	mA
		$\overline{INT}$	3	28 [2]	-	mA
		P port				
		$V_{OL} = 0.5\text{ V}$; $V_{CC} = 1.65\text{ V}$ [3]	8	-	-	mA
		$V_{OL} = 0.7\text{ V}$; $V_{CC} = 1.65\text{ V}$ [3]	9	-	-	mA
		$V_{OL} = 0.5\text{ V}$; $V_{CC} = 2.3\text{ V}$ [3]	8	-	-	mA
		$V_{OL} = 0.7\text{ V}$; $V_{CC} = 2.3\text{ V}$ [3]	10	-	-	mA
		$V_{OL} = 0.5\text{ V}$; $V_{CC} = 3.0\text{ V}$ [3]	8	-	-	mA
		$V_{OL} = 0.7\text{ V}$; $V_{CC} = 3.0\text{ V}$ [3]	10	-	-	mA
		$V_{OL} = 0.5\text{ V}$; $V_{CC} = 4.5\text{ V}$ [3]	8	-	-	mA
		$V_{OL} = 0.7\text{ V}$; $V_{CC} = 4.5\text{ V}$ [3]	10	-	-	mA
V_{OH}	HIGH-level output voltage	P port				
		$I_{OH} = -8\text{ mA}$; $V_{CC} = 1.65\text{ V}$ [4]	1.2	-	-	V
		$I_{OH} = -10\text{ mA}$; $V_{CC} = 1.65\text{ V}$ [4]	1.05	-	-	V
		$I_{OH} = -8\text{ mA}$; $V_{CC} = 2.3\text{ V}$ [4]	2.0	-	-	V
		$I_{OH} = -10\text{ mA}$; $V_{CC} = 2.3\text{ V}$ [4]	1.9	-	-	V
		$I_{OH} = -8\text{ mA}$; $V_{CC} = 3.0\text{ V}$ [4]	2.6	-	-	V
		$I_{OH} = -10\text{ mA}$; $V_{CC} = 3.0\text{ V}$ [4]	2.5	-	-	V
		$I_{OH} = -8\text{ mA}$; $V_{CC} = 4.5\text{ V}$ [4]	4.1	-	-	V
V_{OL}	LOW-level output voltage	P port; $I_{OL} = 8\text{ mA}$				
		$V_{CC} = 1.65\text{ V}$	-	-	0.45	V
		$V_{CC} = 2.3\text{ V}$	-	-	0.30	V
		$V_{CC} = 3.0\text{ V}$	-	-	0.25	V
		$V_{CC} = 4.5\text{ V}$	-	-	0.2	V
I_I	input current	$V_{CC} = 1.65\text{ V to }5.5\text{ V}$				
		SCL, SDA; $V_I = V_{CC}$ or GND	-	-	1	μA
		A0, A1, A2; $V_I = V_{CC}$ or GND	-	-	± 1	μA
I_{IH}	HIGH-level input current	P port; $V_I = V_{CC}$; $V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	1	μA
I_{IL}	LOW-level input current	P port; $V_I = \text{GND}$; $V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	-100	μA

Low-voltage 16-bit I²C and SMBus I/O expander with interrupt output and configuration registers

Symbol	Parameter	Conditions	T _{amb} = -40 °C to +125 °C			Unit
			Min	Typ [1]	Max	
I _{CC}	supply current	SDA, P port, A0, A1, A2; V _I on SDA = V _{CC} or GND; V _I on P port and A0, A1, A2 = V _{CC} ; I _O = 0 mA; I/O = inputs; f _{SCL} = 400 kHz (t _r = 30 ns)				
		V _{CC} = 3.6 V to 5.5 V	-	13	29	μA
		V _{CC} = 2.3 V to 3.6 V	-	6.4	12	μA
		V _{CC} = 1.65 V to 2.3 V	-	3	6.5	μA
		SCL, SDA, P port, A0, A1, A2; V _I on SCL, SDA = V _{CC} or GND; V _I on P port and A0, A1, A2 = V _{CC} ; I _O = 0 mA; I/O = inputs; f _{SCL} = 0 kHz				
		V _{CC} = 3.6 V to 5.5 V	-	1.5	4	μA
		V _{CC} = 2.3 V to 3.6 V	-	0.95	3	μA
		V _{CC} = 1.65 V to 2.3 V	-	0.5	2	μA
		Active mode; P port, A0, A1, A2; V _I on P port, A0, A1, A2 = V _{CC} ; I _O = 0 mA; I/O = inputs; f _{SCL} = 400 kHz (t _r = 30 ns), continuous register read				
		V _{CC} = 3.6 V to 5.5 V	-	15	60	μA
		V _{CC} = 2.3 V to 3.6 V	-	7.4	27	μA
		V _{CC} = 1.65 V to 2.3 V	-	3.5	11	μA
		with pull-ups enabled; P port, A0, A1, A2; V _I on SCL and SDA = V _{CC} or GND; V _I on P port = GND; V _I on A0, A1, A2 = V _{CC} or GND; I _O = 0 mA; I/O = inputs with pull-up enabled; f _{SCL} = 0 kHz				
		V _{CC} = 1.65 V to 5.5 V	-	0.88	1.6	mA
ΔI _{CC}	additional quiescent supply current	SCL, SDA; one input at V _{CC} - 0.6 V, other inputs at V _{CC} or GND; V _{CC} = 1.65 V to 5.5 V	-	-	10	μA
		P port, A0, A1, A2; one input at V _{CC} - 0.6 V, other inputs at V _{CC} or GND; V _{CC} = 1.65 V to 5.5 V	-	-	18	μA
C _i	input capacitance	V _I = V _{CC} or GND; V _{CC} = 1.65 V to 5.5 V	-	1.5	3.5	pF
C _{io}	input/output capacitance	V _{I/O} = V _{CC} or GND; V _D = 1.65 V to 5.5 V	-	3	5	pF

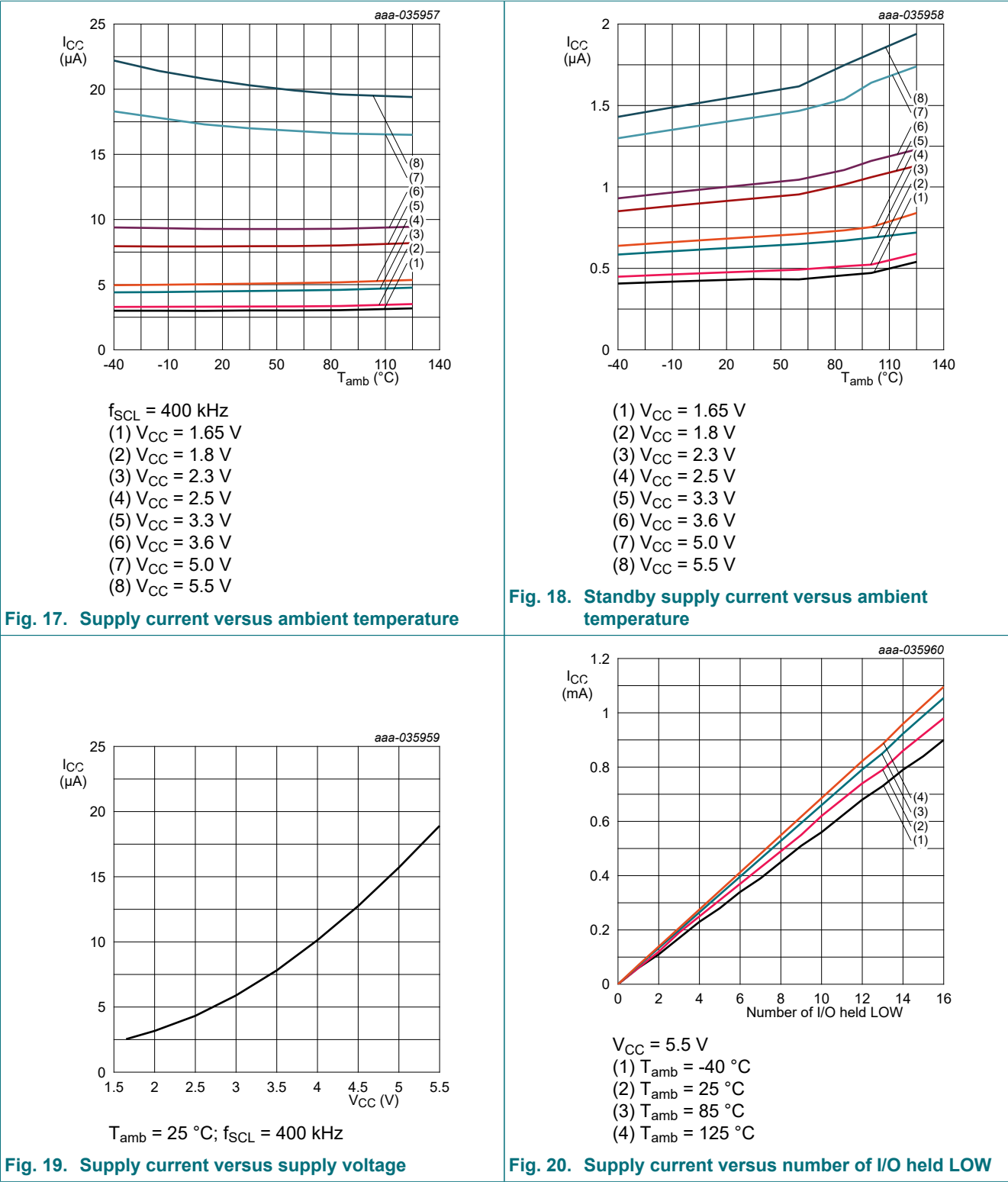
[1] For I_{CC}, all typical values are at nominal supply voltage (1.8 V, 3.3 V or 5 V V_{CC}) and T_{amb} = 25 °C. Except for I_{CC}, the typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C.

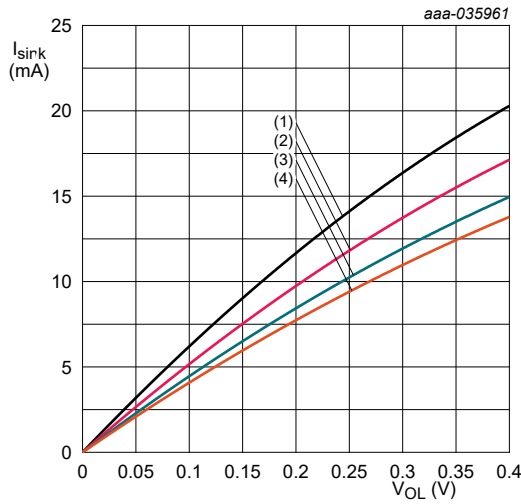
[2] Typical value for T_{amb} = 25 °C. V_{OL} = 0.4 V and V_{CC} = 3.3 V.

[3] Each I/O must be externally limited to a maximum of 25 mA and the device must be limited to a maximum current of 200 mA.

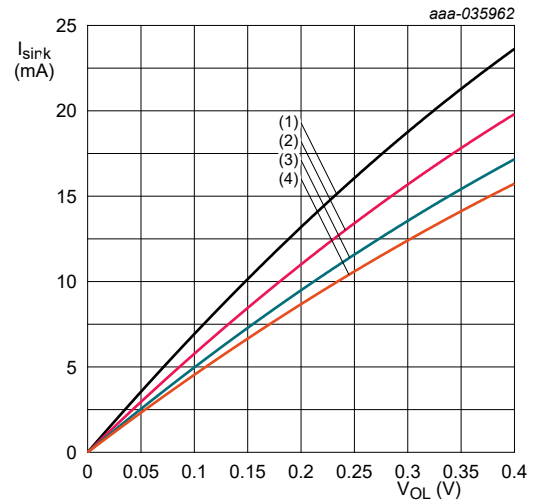
[4] The total current sourced by all I/Os must be limited to 160 mA.

12.1. Typical characteristics

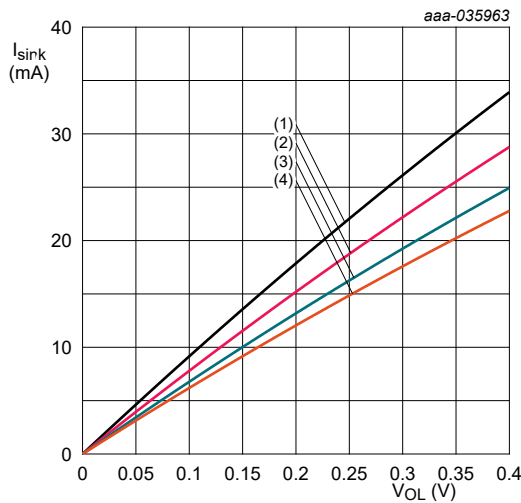




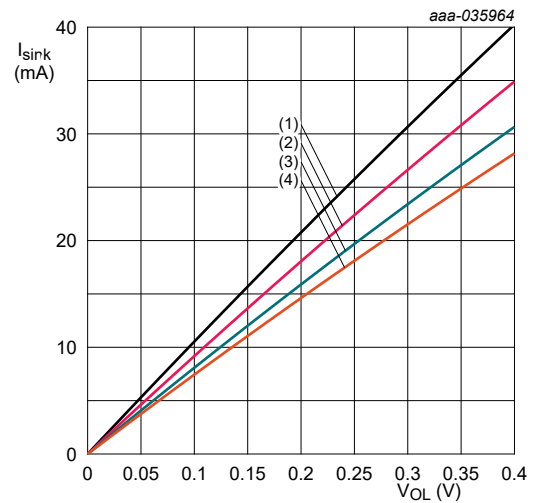
a. $V_{CC} = 1.65 \text{ V}$



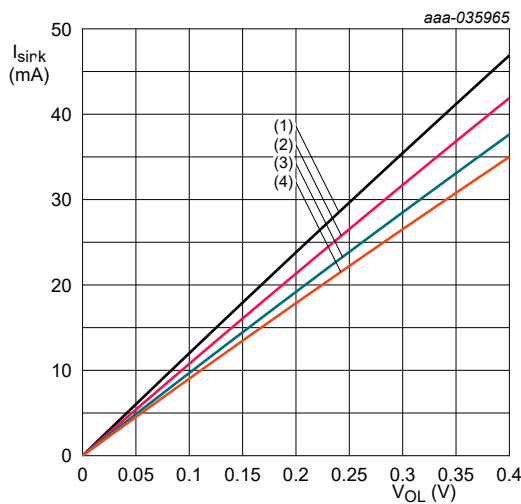
b. $V_{CC} = 1.8 \text{ V}$



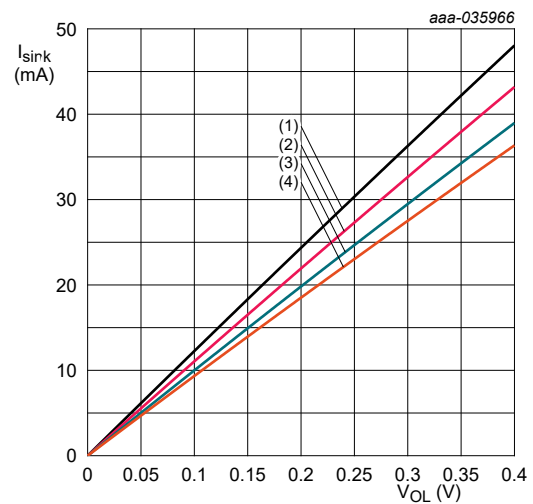
c. $V_{CC} = 2.5 \text{ V}$



d. $V_{CC} = 3.3 \text{ V}$



e. $V_{CC} = 5.0 \text{ V}$



f. $V_{CC} = 5.5 \text{ V}$

- (1) $T_{amb} = -40 \text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 25 \text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 85 \text{ }^{\circ}\text{C}$
- (4) $T_{amb} = 125 \text{ }^{\circ}\text{C}$

Fig. 21. I/O sink current versus LOW-level output voltage

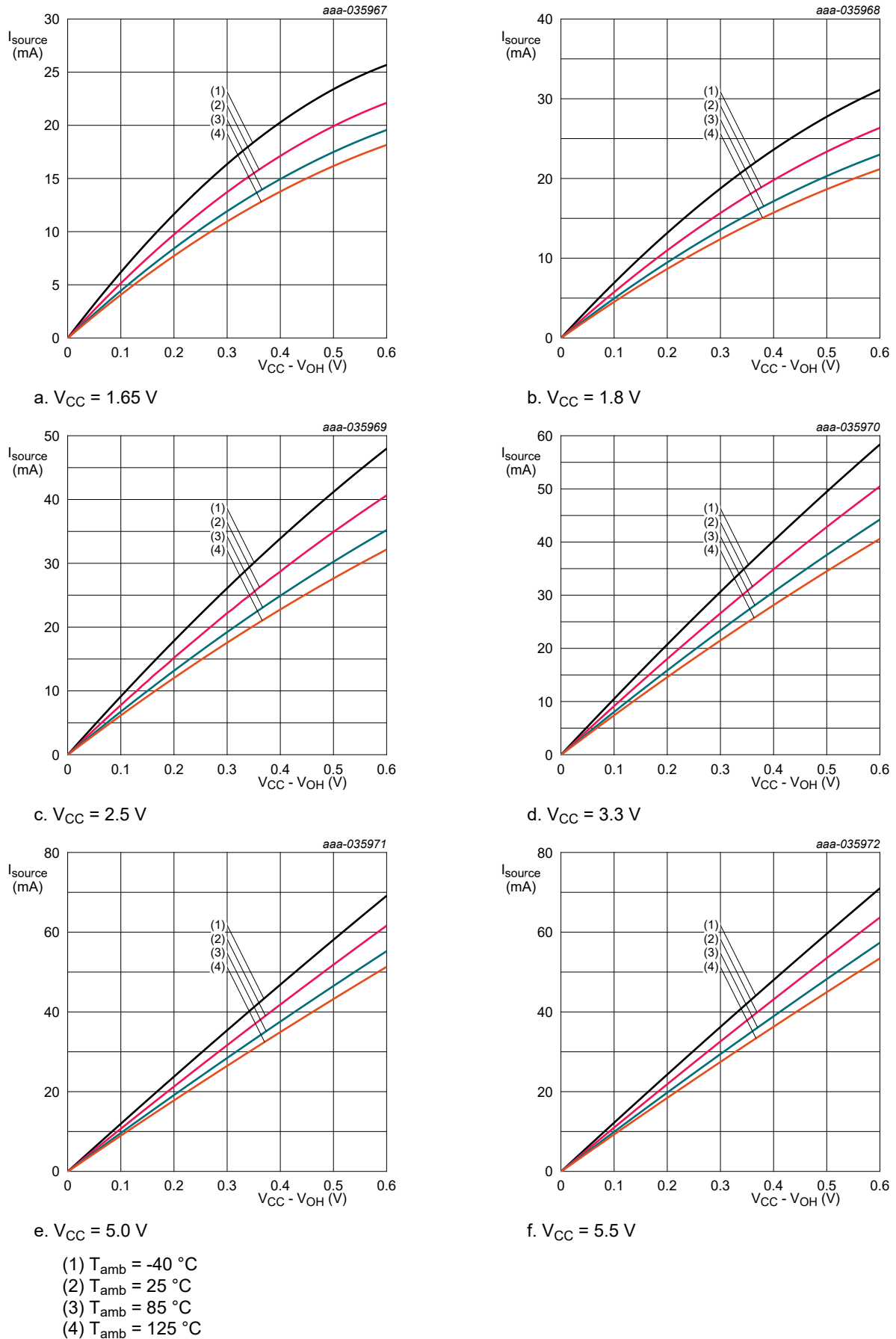
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Fig. 22. I/O source current versus HIGH-level output voltage

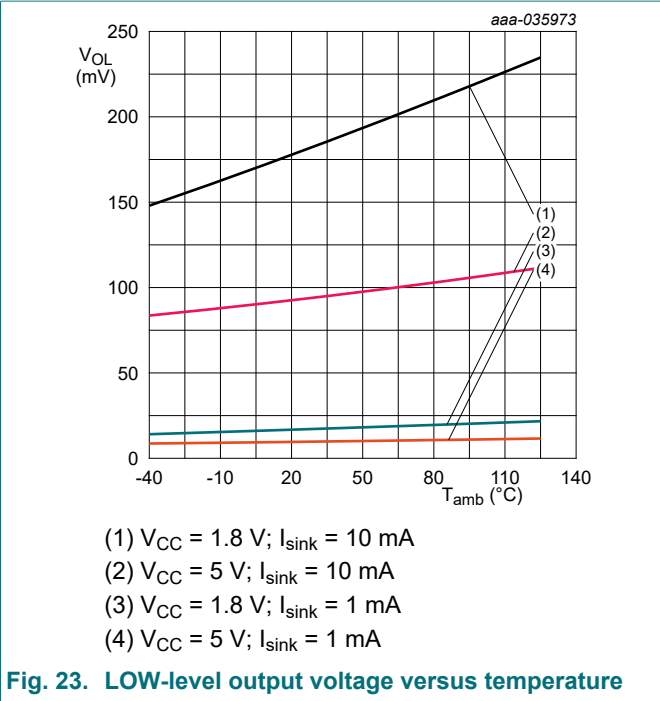


Fig. 23. LOW-level output voltage versus temperature

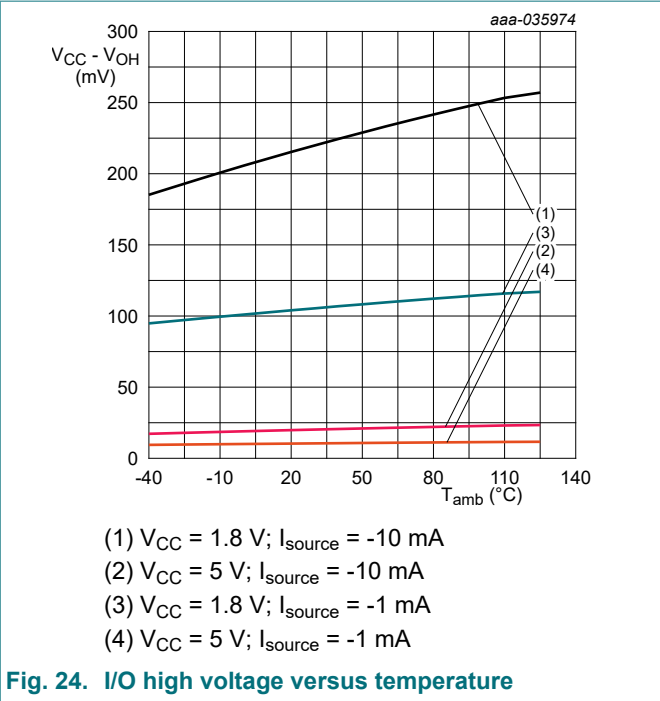


Fig. 24. I/O high voltage versus temperature

13. Dynamic characteristics

Table 17. I²C-bus interface timing requirements

Over recommended operating free air temperature range, unless otherwise specified. See Fig. 25.

Symbol	Parameter	Conditions	Standard-mode I ² C-bus		Fast-mode I ² C-bus		Unit
			Min	Max	Min	Max	
f_{SCL}	SCL clock frequency		0	100	0	400	kHz
t_{HIGH}	HIGH period of the SCL clock		4	-	0.6	-	μs
t_{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	μs
t_{SP}	pulse width of spikes that must be suppressed by the input filter		0	50	0	50	ns
$t_{SU,DAT}$	data set-up time		250	-	100	-	ns
$t_{HD,DAT}$	data hold time		0	-	0	-	ns
t_r	rise time of both SDA and SCL signals		-	1000	20	300	ns
t_f	fall time of both SDA and SCL signals		-	300	$20 \times (V_{CC}/5.5\text{ V})$	300	ns
t_{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	μs
$t_{SU,STA}$	set-up time for a repeated START condition		4.7	-	0.6	-	μs
$t_{HD,STA}$	hold time (repeated) START condition		4	-	0.6	-	μs
$t_{SU,STO}$	set-up time for STOP condition		4	-	0.6	-	μs
$t_{VD,DAT}$	data valid time	SCL LOW to SDA output valid	-	3.45	-	0.9	μs
$t_{VD,ACK}$	data valid acknowledge time	ACK signal from SCL LOW to SDA (out) LOW	-	3.45	-	0.9	μs

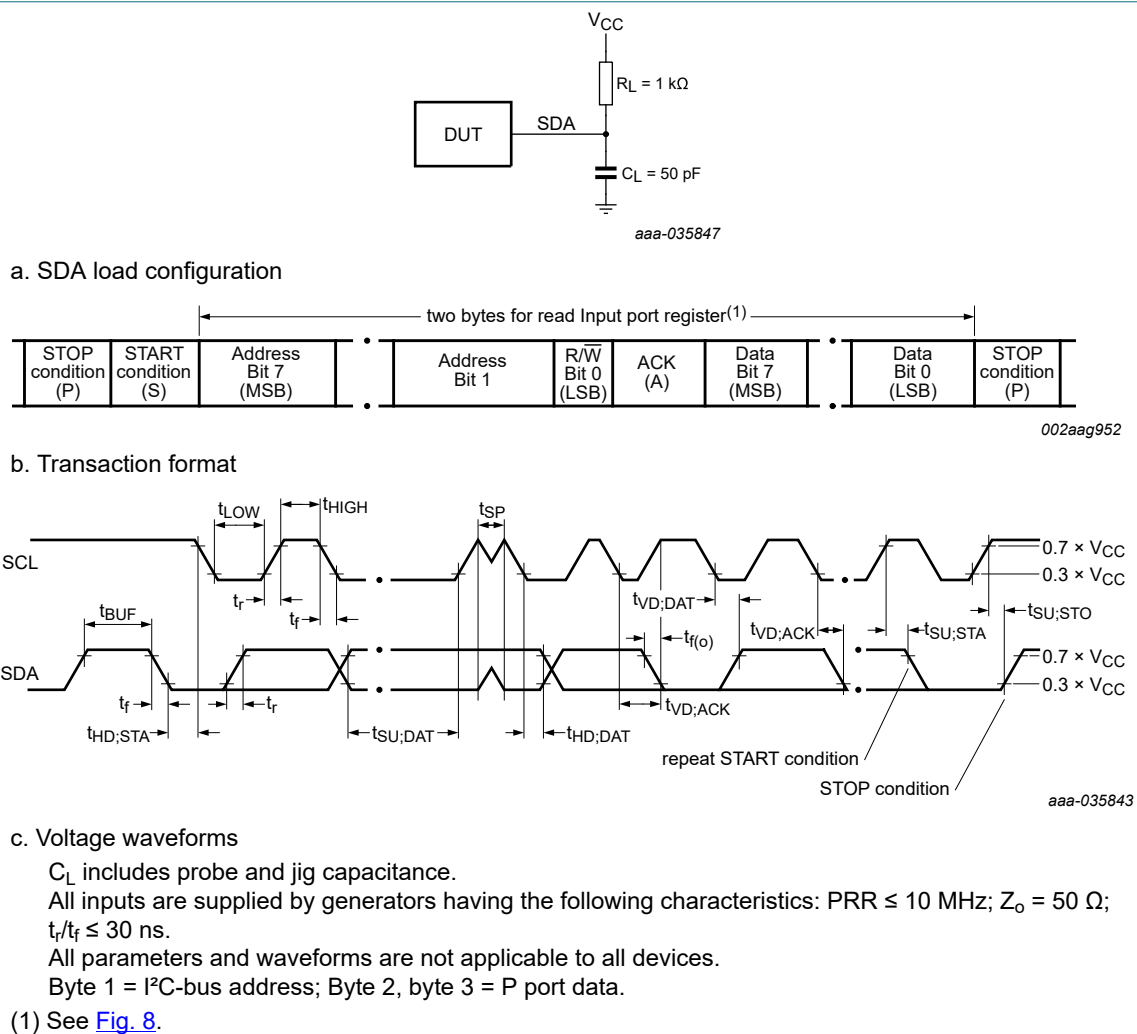
Low-voltage 16-bit I²C and SMBus I/O expander with interrupt output and configuration registers

Table 18. Switching characteristics

Over recommended operating free air temperature range; $C_L \leq 100$ pF; unless otherwise specified. See Fig. 26.

Symbol	Parameter	Conditions	Standard-mode I ² C-bus		Fast-mode I ² C-bus		Unit
			Min	Max	Min	Max	
$t_{V(INT)}$	valid time on pin $\overline{INT}$	from P port to $\overline{INT}$	-	1	-	1	μ s
$t_{rst(INT)}$	reset time on pin $\overline{INT}$	from SCL to $\overline{INT}$	-	1	-	1	μ s
$t_{V(Q)}$	data output valid time	from SCL to P port	-	280	-	280	ns
$t_{su(D)}$	data input set-up time	from P port to SCL	-50	-	-50	-	ns
$t_h(D)$	data input hold time	from P port to SCL	240	-	240	-	ns

14. Parameter measurement information

Fig. 25. I²C-bus interface load circuit and voltage waveforms

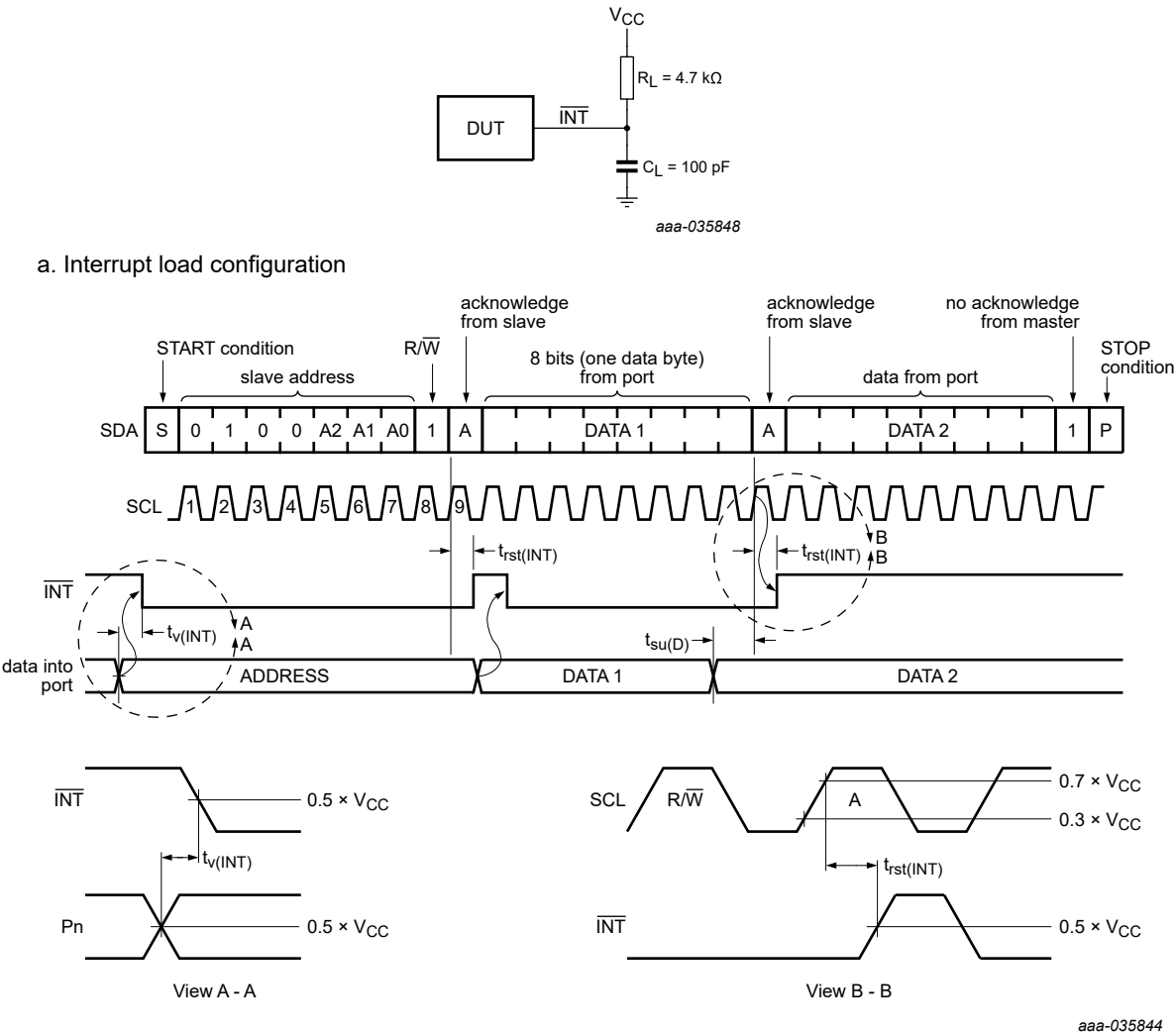


Fig. 26. Interrupt load circuit and voltage waveforms

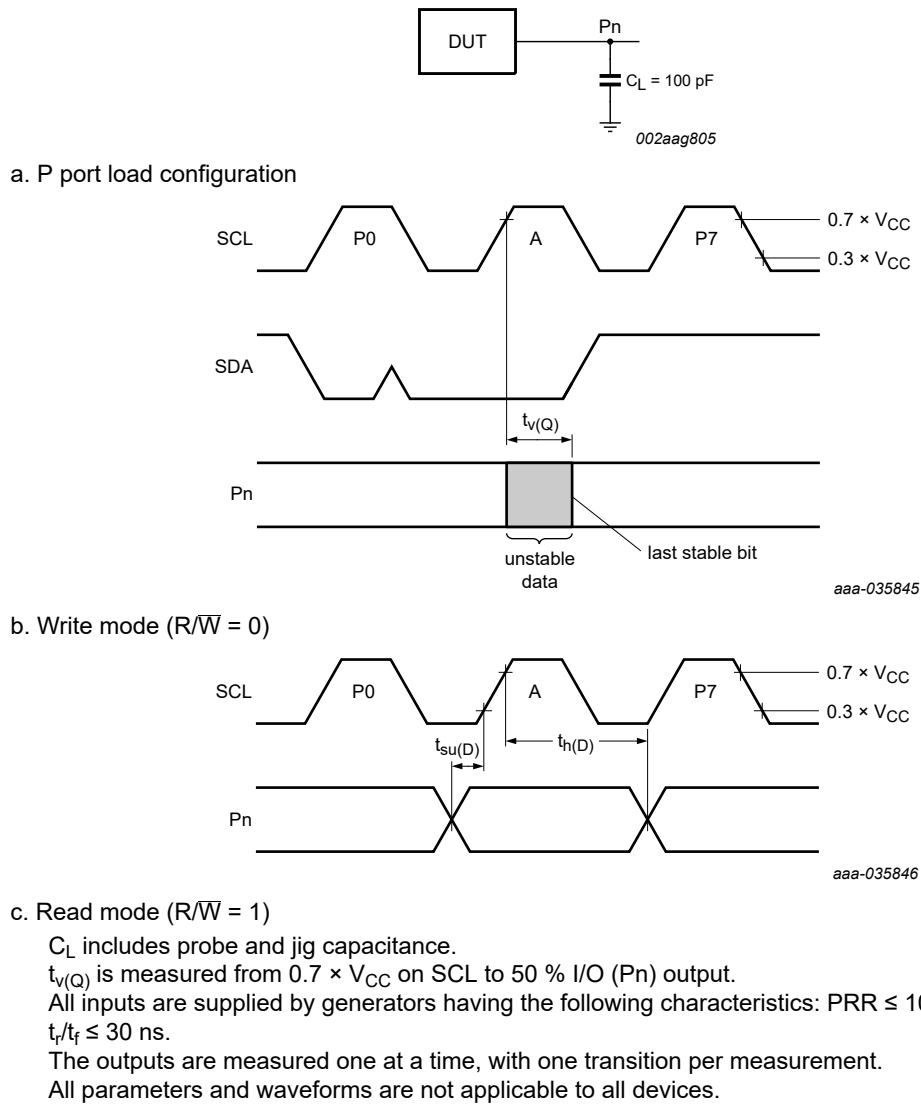


Fig. 27. P port load circuit and voltage waveforms

15. Package outline

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1

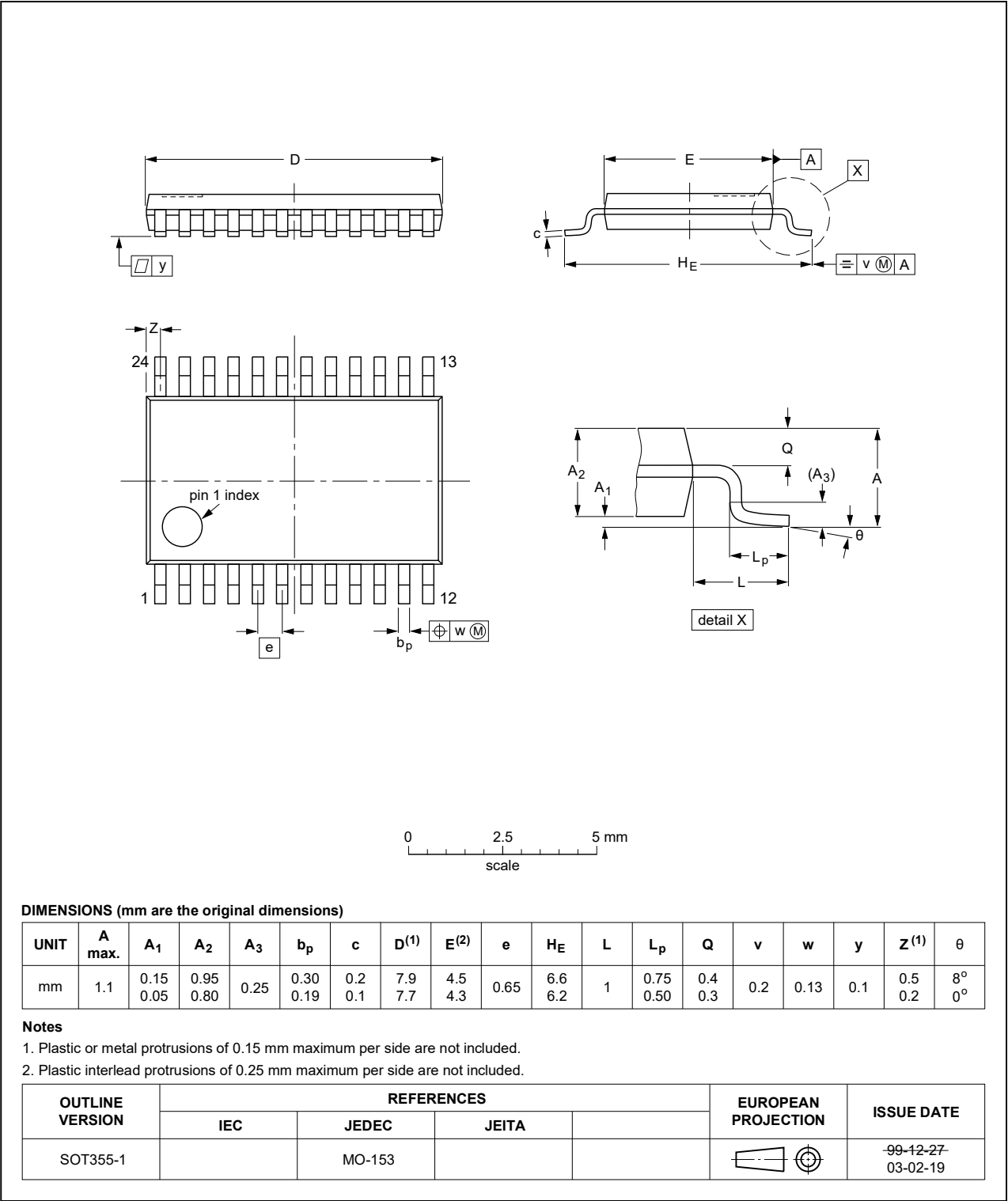


Fig. 28. Package outline SOT355-1 (TSSOP24)

HWQFN24: plastic thermal enhanced very very thin Quad Flat packages, no leads;
24 terminals; 0.5 mm pitch; 4 x 4 x 0.75 mm body

SOT8041-1

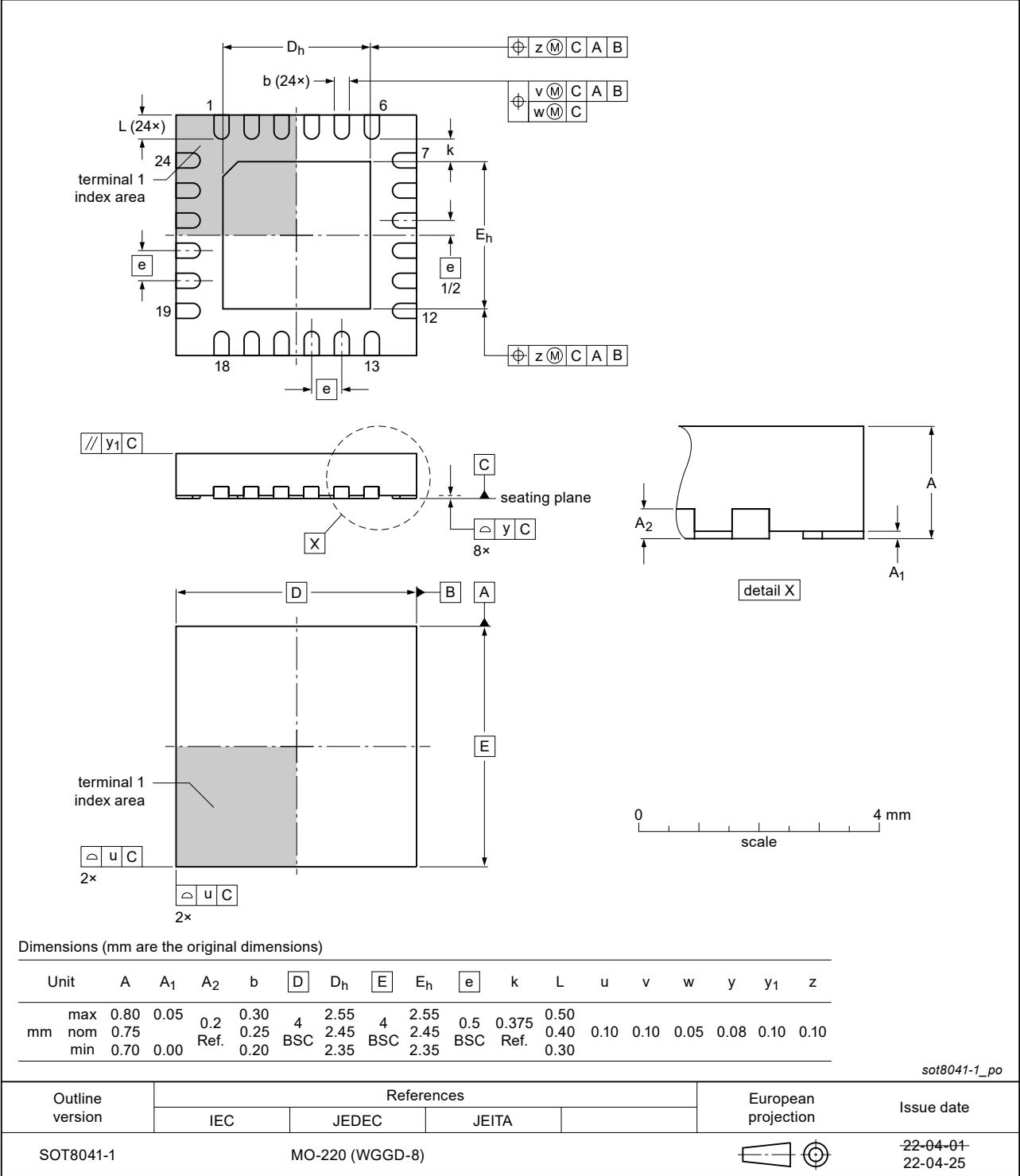


Fig. 29. Package outline SOT8041-1 (HWQFN24)

16. Abbreviations

Table 19. Abbreviations

Acronym	Description
ACPI	Advanced Configuration and Power Interface
ANSI	American National Standards Institute
CBT	Cross-Bar Technology
CDM	Charged-Device Model
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
FET	Field-Effect Transistor
FF	Flip-Flop
GPIO	General Purpose Input/Output
HBM	Human Body Model
I ² C-bus	Inter-Integrated Circuit bus
I/O	Input/Output
JEDEC	Joint Electron Device Engineering Council
LED	Light-Emitting Diode
SMBus	System Management Bus

17. Revision history

Table 20. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NCA9555_Q100 v.3.1	20240805	Product data sheet		NCA9555_Q100 v.3
NCA9555_Q100 v.3	20230424	Product data sheet		NCA9555_Q100 v.2
Modifications	• Errata: labels in the NC9555BY pinning diagram corrected. Table 2 corrected.			
NCA9555_Q100 v.2	20230330	Product data sheet		NCA9555_Q100 v.1
Modifications	• Type number NCA9555BY-Q100 (SOT8041-1/HWQFN24) added.			
NCA9555_Q100 v.1	20230220	Product data sheet	-	-

18. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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